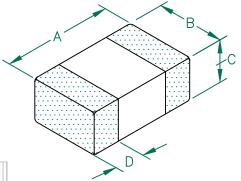
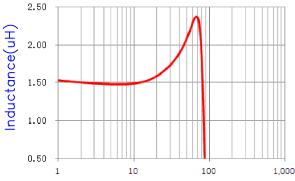
CPI1008K1R8R-10

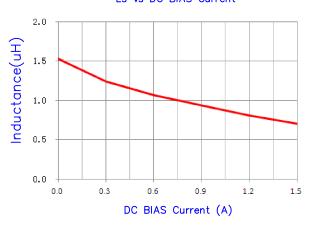
PHYSICAL DIMENSIONS:



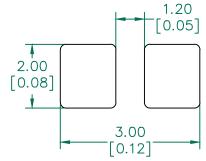




Frequency (MHz)
Ls vs DC BIAS Current



LAND PATTERNS FOR REFLOW SOLDERING



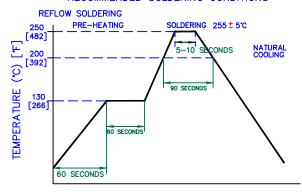
(For wave soldering, add 0.763 [0.030] to this dimension)

	ELECTRICAL CHARACTERISTICS:										
	L (μΗ) @ 1MHz ± 20%	DCR (Ω)	l (Max)								
Nom	1.80										
Min	1.44										
Max	2.16	0.1625	1500mA								

NOTES: UNLESS OTHERWISE SPECIFIED

- TAPED AND REELED per CURRENT EIA SPECIFICATIONS
 REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)
- 6. COSMETIC SPECIFICATION REFER TO WI-QA-124.

RECOMMENDED SOLDERING CONDITIONS





_														
L	DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird									
					Tech, and is loaned in confidence subject to return upon request		dlaird							
Γ					with the understanding that no									
Γ					copies shall be made without th written consent of Laird Tech. A			u	II W					
Γ					rights to design or invention are		_							
Г					reserved.									
T	D	CHANGE DCR	07/13/17	QIU	PROJECT/PART NUMBER:		REV PART T			DRAWN BY:				
	С	UPDATE PAD DIMENSION ROHS	07/08/14	QU	CPI1008K1R8R-10	-	ע ן	CO-FIRE		QU				
	В	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11	SCA	NTS		SHEET:					
Γ	Α	ORIGINAL DRAFT	03/01/11	QU	, ,	TOO								
Γ	REV	DESCRIPTION	DATE	INT	CPI1008K1R8R-10-D				1	of 1				